

Multicore Solder Paste

Product Images



Description

- Outstanding humidity resistance
- Superior slump resistance
- Colourless, soft, non-stick, pin-testable residue
- Optimised paste viscosity
- Extended open time and tack life
- Halide-free flux classification
- High tack force
- Long printer abandon times
- Excellent solderability
- Wide printing and reflow process windows

Production Equipment Europe
Superior Service – Single Source